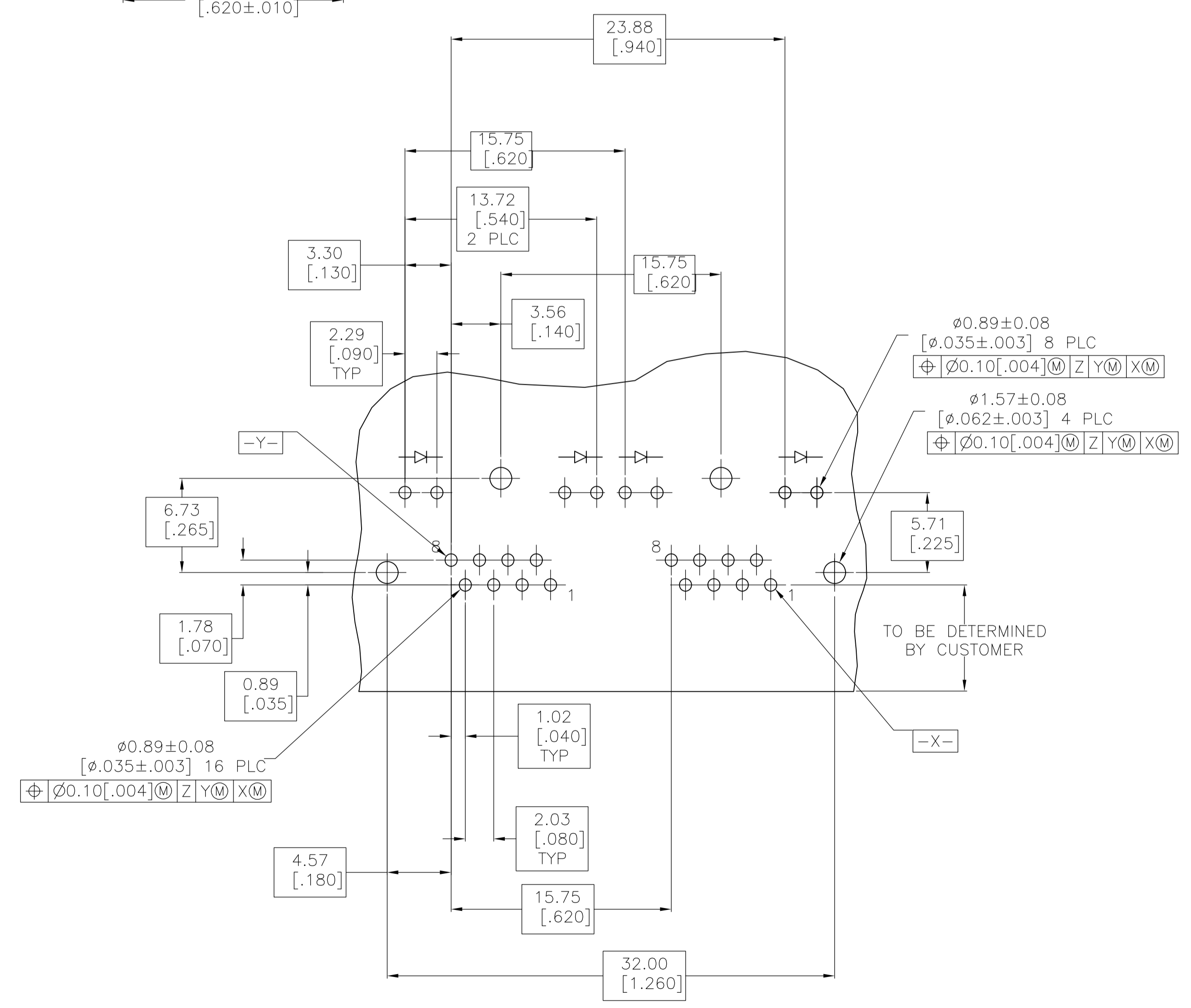


- MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0  
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MIN THICK NICKEL.  
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MIN SATIN NICKEL WITH 2.03µm[.000080] MIN TIN POST DIPPED ON PCB GROUND TABS  
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
▲ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.  
△ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE

GREEN	GREEN	1364173-5
YELLOW	GREEN	1364173-1
POSITION 2	POSITION 1	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN: M.MORRIS	OBJANOD	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK: D.DIXON	OBJANOD	NAME: INVERTED MODULAR JACK ASSEMBLY, 1X2, PANEL GROUND, SHIELDED, NO MOUNTING LEGS, WITH LEDS	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: D.DIXON	OBJANOD	PRODUCT SPEC: 108-1163-4	
0 PLC ± -		APPLICATION SPEC: 114-2154		SIZE: 114-2154	
1 PLC ± -		DRAWING NO: 100779		RESTRICTED TO: -	
2 PLC ± 0.25[.01]		SCALE: 4:1		SHEET 1 OF 1	
3 PLC ± 0.13[.005]		REV: C		REV: C	
4 PLC ± -		CUSTOMER DRAWING		REV: C	